

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3965788

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TINI ALLOY COMPANY	05/14/2012
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	NSVASCULAR, INC.
<b>Street Address:</b>	10960 WILSHIRE BLVD
<b>Internal Address:</b>	SUITE 1230
<b>City:</b>	LOS ANGELES
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	90024
<b>PROPERTY NUMBERS Total: 7</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	60211352
Application Number:	60177881
Application Number:	10345782
Application Number:	11027814
Patent Number:	6533905
Patent Number:	7981258
Patent Number:	8506767
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)202-3001
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2146515000
<b>Email:</b>	allison.hung@haynesboone.com
<b>Correspondent Name:</b>	HAYNES AND BOONE, LLP
<b>Address Line 1:</b>	2323 VICTORY AVENUE
<b>Address Line 2:</b>	SUITE 700
<b>Address Line 4:</b>	DALLAS, TEXAS 75219
<b>ATTORNEY DOCKET NUMBER:</b>	49317.1
<b>NAME OF SUBMITTER:</b>	MICHAEL YOO
<b>SIGNATURE:</b>	/MICHAEL YOO/

PATENT

<b>DATE SIGNED:</b>	07/18/2016
<b>Total Attachments: 3</b> source=49317.1 Executed Assignment (TiNi to NSVascular)#page1.tif source=49317.1 Executed Assignment (TiNi to NSVascular)#page2.tif source=49317.1 Executed Assignment (TiNi to NSVascular)#page3.tif	

**Exhibit B**  
**Form of Patent Assignment**

**PATENT ASSIGNMENT**

This Patent Assignment (this "Patent Assignment") is delivered pursuant to that certain PATENT ASSIGNMENT AGREEMENT (the "Agreement"), effective as of May 11, 2012, by and between NSVascular, Inc., a Delaware Corporation ("NSV"), having its principal place of business at 10960 Wilshire Blvd., Suite 1230, Los Angeles, CA 90024 and TiNi Alloy Company ("Assignor") Capitalized terms used in this Patent Assignment without definition have the respective meanings given to them in the Agreement

Assignor is the owner of all right, title and interest in and to the patents, patent applications and invention disclosures specifically listed in Annex A to this Patent Assignment (the "IP Rights"). NSV is desirous of acquiring all of the Seller's rights in the IP Rights. Assignor has delivered this instrument signed by Assignor to enable NSV to file it with any appropriate governmental authority to indicate ownership of the Intellectual Property described below and for the other purposes set forth in this instrument. This instrument supplements and is in addition to all other rights of NSV under the Agreement and other instruments of transfer delivered in connection with the Agreement.

NOW, THEREFORE, for good and valuable consideration, receipt of which Assignor acknowledges, and by signing and delivering this instrument, Assignor sells, assigns, transfers, conveys, and delivers to the Purchaser all of the Seller's right, title, and interest in and to:

- (a) the IP Rights; and
- (b) the following properties and rights with respect to the IP Rights:
  - (i) the inventions claimed or described in the patents or applications;
  - (ii) any patents in the United States and anywhere else in the world and patent applications that have been or may be granted or filed, respectively, with respect to those inventions, including without limitation all foreign patents that may claim priority based on and correspond to the patents listed in Annex A;
  - (iii) all divisions, renewals, reissues, continuations, extensions and continuations-in-part of the foregoing patents;
  - (iv) all income, royalties, damages and payments due or payable to the Seller with respect to the patents, including without limitation unpaid damages and payments for past, present and future infringements of any patent; and
  - (v) all rights to sue and recover damages and payments for past, present and future infringements of any of the patents, including the right to fully and entirely replace the Seller in all related matters.

The foregoing rights in and under the IP Rights shall apply to the full end of their terms as fully as Assignor would have held the same in the absence of this assignment. As of the date set forth below, the Purchaser has succeeded to all right, title and standing of Assignor to (a) receive all rights and benefits pertaining to the IP Rights, and (b) commence, prosecute, defend and settle all claims and take all actions that NSV, in its sole discretion, may elect in relation to the IP Rights. This Patent Assignment (a) is irrevocable and effective upon the Assignor's signature to and delivery of a manually signed copy of this instrument or facsimile or email transmission of the signature to this instrument, (b) benefits and binds the parties to the Agreement and their respective successors and assigns, (c) does not modify or affect, and is subject to, the provisions of the Agreement and (d) may be signed in counterparts.

The undersigned has signed this Patent Assignment on 14 May, 2012.

TiNi Alloy Company

By: Alfred David Johnson  
Name: ALFRED DAVID JOHNSON  
Title: PRESIDENT

STATE OF: California  
COUNTY OF: Alameda

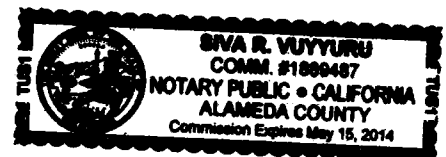
On MAY 14<sup>th</sup> 2012 before me, SIVA R. VUYYURU (the undersigned notary), personally appeared Alfred David Johnson personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument and acknowledged to me that he/~~she~~ executed the same in his/~~her~~ authorized capacity, and that by his/~~her~~ signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

Witness my hand and official seal.

S. R. Vuyyuru  
Notary Public

My commission expires: MAY 15 2014

(Notary Seal)



## ANNEX A TO PATENT ASSIGNMENT

### Registered Patents

Patent	Registration No. and Country	Issue Date
Method for Sputtering TiNi Shape Memory Alloys	US 6533905	3/18/2003
Method of Accurately Measuring Compositions of Thin Film Shape Memory Alloy	US 6620634	9/16/2003
Methods of Fabricating High Transition Temperature SMA, and SMA Materials Made by the Methods	US 6669795	12/30/2003
Three Dimensional Thin Film Devices and Methods of Fabrication	US 6746890	6/8/2004
Method of Fabrication of Free Standing Shape Memory Alloy Thin Film	US 6790298	9/14/2004
Shape Memory Alloy Thin Film, Method of Fabrication, and Articles of Manufacture	US 7540899	6/2/2009
Tear-Resistant Thin Film Methods of Fabrication	US 7763342	7/27/2010
Thin-Film Shape Memory Alloy Device and Method	US 7981258	7/19/2011
Method and Devices for Preventing Restenosis in Cardiovascular Stents	US 8007674	8/30/2011

### Pending Patent Applications

Patent	Application Number and Country	Application Date
Three Dimensional Thin Film Devices and Methods of Fabrication	Europe	